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AMEDMENTS

FOR THE CLAIMS

Claim 1. (Currently amended) A flip chip package structure, comprising:

a chip having a first bump-positioning region;

a substrate having a second bump-positioning region, at least a first hole and a plurality of second holes, wherein the first hole and the second holes are located within the second bump-positioning region, and the first hole has a depth greater than the second holes;

at least a first bump arranged between the first bump-positioning region of the chip and the second bump-positioning region of the substrate, wherein the first bump and the substrate are bonded together via the first hole; and

a plurality of second bumps arranged between the first bump-positioning region of the chip and the second bump-positioning region of the substrate, wherein the second bumps and the substrate are bonded together via the second holes;

wherein the first bump has a volume larger than a volume of the second bump.

Claim 2. (original) The flip chip package structure of claim 1, wherein when there is one first bump and one first hole, the first bump is located in the middle of the first bump-positioning region of the chip and the first hole is located in the middle of the second bump-positioning region.

Claim 3. (original) The flip chip package structure of claim 1, wherein when there are two first bumps and two first holes, the two first bumps are positioned between the chip and the substrate and symmetrical relative to a centroid of the first bump-positioning region, and the two first holes are positioned in the second bump-positioning region and symmetrical relative to a centroid of the second bump-positioning region.

Claim 4. (original) The flip chip package structure of claim 1, wherein the package structure has a plurality of first bumps and the first bumps are located close to corners of the first bump-positioning region and located between the chip and the substrate, and the substrate has a plurality of first holes and the first holes are positioned close to corners of the second bump-positioning region.

Claim 5. (original) The flip chip package structure of claim 1, wherein the first bump arranged between the chip and the substrate physically but not electrically connects the chip and the substrate.

Claim 6. (original) The flip chip package structure of claim 1, wherein the first bump arranged between the chip and the substrate electrically and physically connects the chip and the substrate.

Claim 7. (original) The flip chip package structure of claim 1, further comprising a filler material disposed between the chip and the substrate and encapsulating the first bumps and the second bumps.

Claims 8-14. Cancelled.

Claim 15. (currently amended) The flip chip package structure of claim 18, wherein the first bump further comprises:

a conductive pillar arranged on the chip; and

a soldering block arranged on the conductive pillar.

Claim 16. (currently amended) The flip chip package structure of claim 18, wherein the first bump has a height ranging from about 150 μm to about 200 μm.

Claims 17-26. Cancelled.

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